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QM3016D N-Channel 30V Fast Switching MOSFET

General Description

The QM3016D is a high performance trench N-channel MOSFET which utilizes extremely high cell density to provide low Rdson and gate charge characteristics. It is ideally suited to support synchronous buck converter applications.

The QM3016D meets RoHS and Green Product requirements while supporting full function reliability.

Features

- ✓ Advanced high cell density Trench technology
- ✓ Super Low Gate Charge
- ✓ Excellent CdV/dt effect decline
- ✓ Green Device Available

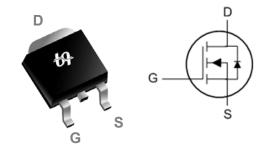
Product Summary

V _{DS}	R _{DS(ON)} max (V _{GS} =10V)	Ι _D (Tc=25 °C)		
30V	4mΩ	96A		

Applications

- ✓ High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- ✓ Networking DC-DC Power System
- ✓ Load Switch

Pin Configuration



Ordering Information

Order Number	Package Type	Top Marking		
QM3016D	TO252	Weekly Code Yearly Code Logo Sequence Assembly Code		

QM3016D-DS-F0000, Jul. 2019

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Absolute Maximum Ratings

Symbol	Parameter	R	Rating		
Symbol	Parameter	10s Steady State		Units	
VDS	Drain-Source Voltage		30		
Vgs	Gate-Source Voltage		±20	V	
I₀@Tc=25°C	Continuous Drain Current, V _{GS} @ 10V ¹		96	Α	
I _D @T _C =100°C	Continuous Drain Current, V _{GS} @ 10V ¹		68		
ID@TA=25°C	Continuous Drain Current, V _{GS} @ 10V ¹	30	19	Α	
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	25	16	Α	
IDM	Pulsed Drain Current ²		192 317 53.8 62.5		
EAS	Single Pulse Avalanche Energy ³				
las	Avalanche Current				
P _D @T _C =25°C	Total Power Dissipation ⁴	(
PD@TA=25°C	Total Power Dissipation ⁴	6	2.42	W	
Tstg	Storage Temperature Range	-55	-55 to 175		
TJ	Operating Junction Temperature Range	-55	-55 to 175		

Thermal Data

Symbol Parameter		Тур.	Max.	Unit
R _{0JA}	R _{0JA} Thermal Resistance Junction-Ambient ¹		62	°C/W
R _{0JA}	Thermal Resistance Junction-Ambient ¹ (t \leq 10s)		25	°C/W
R _{0JC} Thermal Resistance Junction-Case ¹			2.4	°C/W



N-Channel Electrical Characteristics

N-Channel Electrical Characteristics: (T」=25 ${}^\circ\!{}_{ m C}$, unless otherwise noted)							
Symbol	Parameter	Conditions	Min	Тур	Max	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	30			V	
$\triangle BV_{DSS} / \triangle T_J$	BVDSS Temperature Coefficient	Reference to 25°C, I _D =1mA		0.0213		V/°C	
Deserve	Static Drain-Source	V _{GS} =10V, I _D =30A		3.4	4		
Rds(on)	On-Resistance ²	V _{GS} =4.5V , I _D =15A		5.2	6	mΩ	
V _{GS(th)}	Gate Threshold Voltage		1.0	1.5	2.5	V	
$ extstyle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	V _{GS} =V _{DS} , I _D =250uA		-5.73		mV/°C	
I	Drain Course Lookage Current	V _{DS} =24V, V _{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =24V, V _{GS} =0V , T _J =55°C			5	uA	
Igss	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =30A		26.5		S	
R _g	Gate Resistance	$V_{\text{DS}}\text{=}0\text{V}$, $V_{\text{GS}}\text{=}0\text{V}$, f=1MHz		1.4	2.8	Ω	
Qg	Total Gate Charge			31.6			
Q _{gs}	Gate-Source Charge	V _{DS} =15V, V _{GS} =4.5V, I _D =15A		8.6		nC	
Q_{gd}	Gate-Drain Charge			11.7			
t _{d(on)}	Turn-On Delay Time			9			
tr	Rise Time	V _{DS} =15V, V _{GS} =10V, R _G =3.3Ω,		19			
t _{d(off)}	Turn-Off Delay Time	I _D =15A		58		ns	
t _f	Fall Time			15.2			
Ciss	Input Capacitance			3075	4000		
Coss	Output Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz		400	530	pF	
Crss	Reverse Transfer Capacitance			315			



Guaranteed Avalanche Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
EAS	Single Pulse Avalanche Energy⁵	$V_{\text{DD}}\text{=}25\text{V}$, L=0.1mH , $I_{\text{AS}}\text{=}30\text{A}$	98			mJ

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
ls	Continuous Source Current ^{1,6}	- V _G =V _D =0V, Force Current			96	А
Ism	Pulsed Source Current ^{2,6}				192	А
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25°C			1	V
t _{rr}	Reverse Recovery Time	I⊧=30A , di/dt=100A/µs,		18		nS
Qrr	Reverse Recovery Charge	TJ=25°C		8		nC

Note:

1. Test data conducted with surface mount attachment to 1 inch², FR-4 board utilizing 2oz copper

2. Pulse Test. Pulse width \leq 300uS, duty cycle \leq 2%

3. EAS data is a maximum rating. The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH

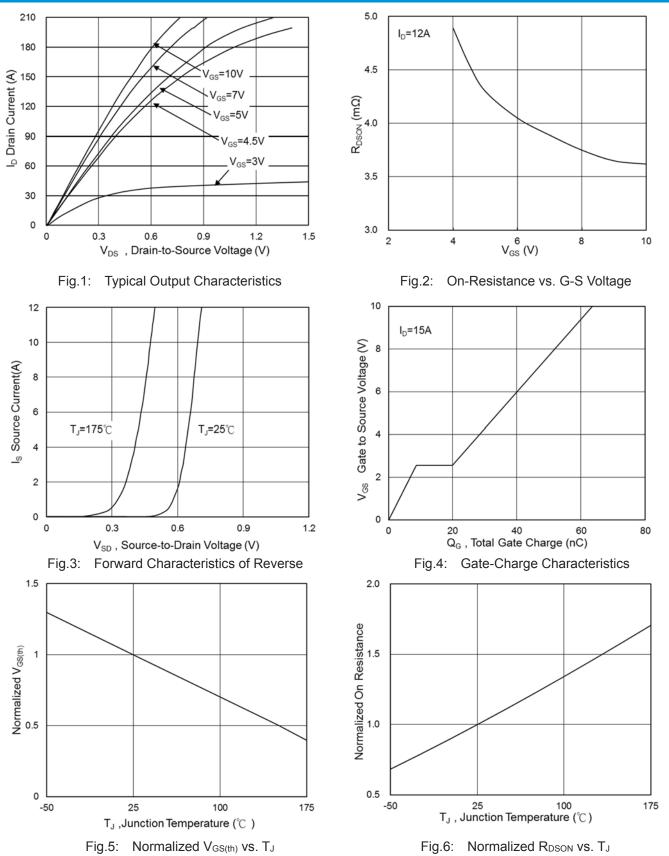
4. The power dissipation is limited by a 175°C maximum junction temperature

5. The Min. value is 100% EAS tested guarantee

6. The data is theoretically the same as I_D and I_{DM} . In real applications, it will be limited by total power



Typical Characteristics



QM3016D-DS-F0000, Jul. 2019



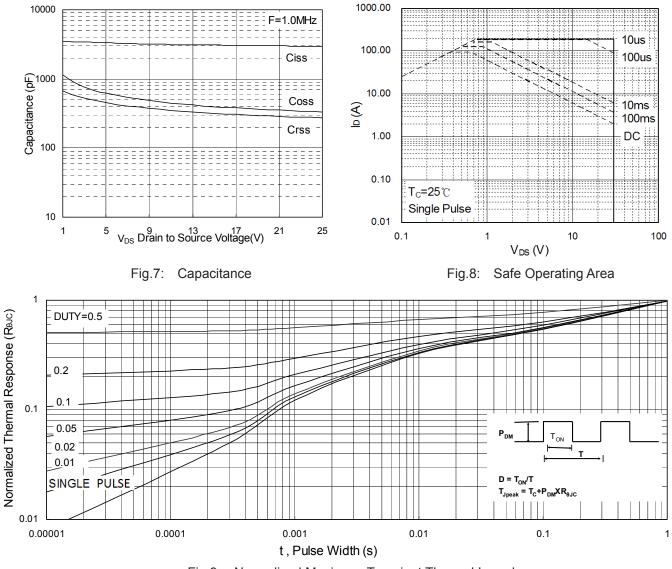


Fig.9: Normalized Maximum Transient Thermal Impedance



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uPI Semiconductor Corp.

9F.,No.5, Taiyuan 1st St. Zhubei City, Hsinchu, Taiwan, R.O.C. TEL : 886.3.560.1666 FAX : 886.3.560.1888